How to write a paper for IEEE?

Eszter Lukács

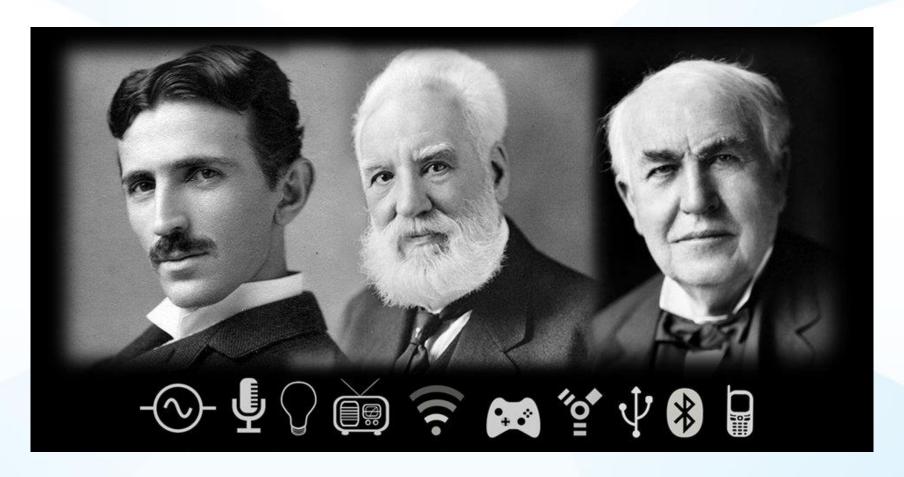
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1884: Where we came from





About the IEEE

- World's largest technical membership association with more than 430,000 members in over 160 countries
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- Four Core areas of activity
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 - Conferences organizer
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RUSSIA SIBERIA SECTION

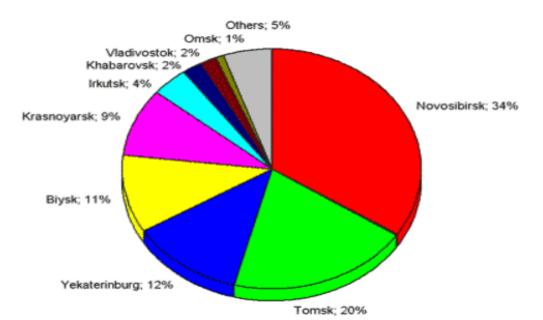
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About IEEE

Founded in 1884, the IEEE is a non-profit organization, and has more than 410,000 individual members in 150 countries. Through its members, the IEEE is a catalyst for technological innovation. IEEE is a leading authority in a broad range of areas such as computer engineering, electric power, aerospace and consumer electronics, biomedical technology, and telecommunications, naming only a few. IEEE publishes 30 percent of the world's literature in electrical engineering, computers and control technology, and hold more than 300 major conferences and 6,000 local meetings annually. Recognized as essential guides for every industry, more than 900 active IEEE standards are in use today with 700 currently in development.

About IEEE Russia Siberia Section

On 13 February 2003 IEEE Russia Siberia Section has been established through the split of the Russia Moscow section. Russia Siberia Section has the strong potential for membership growth through its big cities at Ural (in the order of population decreasing: Yekaterinburg, Chelyabinsk, Tyumen, etc.), Siberia (Novosibirsk, Omsk, Krasnoyarsk, Irkutsk, Barnaul, Novokuznetsk, Kemerovo, Tomsk, Ulan-Ude, Chita, etc.) and the Far-East (Vladivostok, Khabarovsk, etc.) Federal Districts of Russia.



Welcome to the Russia Siberia Section Website!

In this era of the World Wide Web, it is inevitable that we reach out to our colleagues, especially students via the most common source of information to most of us, the Internet. This website contains all information about us – events and conferences, membership, papers and some fun photos and pictures. The site provides the best services to members registered in our Section as well as introducing non-members to the exciting world of the IEEE.

useful Here will find information about our activities that we make, as well as some of our history and achieved goals. We are aware of being in a dynamic world, where changes in technology, knowledge and culture are happening at an increasing pace, even more in the Science and Engineering fields. These changes obligate us to a quick and permanent adaptation. In this respect, our Section give to the whole professional community the knowledge and experience that make possible the scientific and technical updating, satisfying the



Tomsk IEEE Chapter & Student Branch of The Institute of Electrical and Electronics Engineers (IEEE)



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The Tomsk State University of Control Systems and Radioelectronics IEEE Student Branch was formed in 2000. It is the 3rd IEEE Student Branch in Russia. The branch is active in promoting the IEEE through exciting and informative events ranging from technical seminars to careers events as well as professional conferences. We hope that these events help our members gain valuable knowledge and skills as well as being enjoyable.



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Tomsk IEEE Chapter

The Tomsk Joint AP/COM/ED/MTT/EMC Chapter was established in 2000. We are active in promoting the IEEE membership among researches in Tomsk and all Siberia. The Chapter established and take place the International Siberian Conference on Control and Communications. This conference is

Welcome!

This is the web portal for the Tomsk IEEE Chapter & Student Branch, to communicate with our members and anyone interested in technology and knowledge. The main purpose of the IEEE Tomsk is the dissemination of the theory and practice of all aspects of electrical engineering, electronics, radio, allied branches of engineering or related arts and sciences, as well as the furtherance of the professional development

Virtual IEEE Siberia Section



Objectives and Aims

We always aim to provide a lot of events and activities to our members, and to bridge the gap between the student body and the professional organization.

Our primary goals is following:

- · Increase the number of IEEE SB members
- · Greater participation in organized events
- · Organize more technical and social meetings, on a wide variety of topics
- · Increase the number of careers related events

Conferences and Seminar

Sibcon

International Siberian
Conference on Control and
Communications

Sibinfo

Student paper Contest and Conference on the Information Security

Seminar

Tomsk Seminar "The Intellectual Systems of Modeling, Design and Control"



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IEEE publishes:

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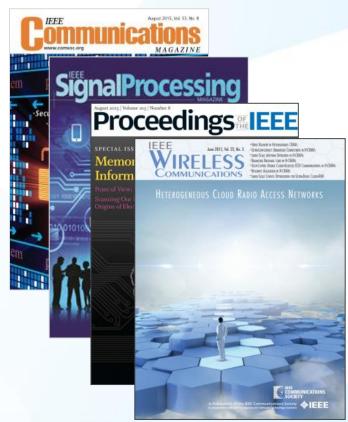


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- # 1 in Manufacturing Engineering
- # 1 in Theory and Methods
- # 1 in Telecommunications
- # 2 in Electrical Engineering
- # 3 in Aerospace Engineering



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IEEE and Patents



IEEE research powers new patents



Analysis of Patent Referencing to IEEE Papers, Conferences, and Standards 1997-2014

Report prepared for:

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Report prepared by:

1790 Analytics LLC 130 Haddon Avenue Haddonfield, NJ 08033 www.1290analytics.com

May 14, 2015

A study of the top 40 patenting organizations ranks IEEE #1 again

- Over three times more citations than any other publisher
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- The importance of sci-tech literature in patents is rising
- IEEE research is increasingly valuable to innovators

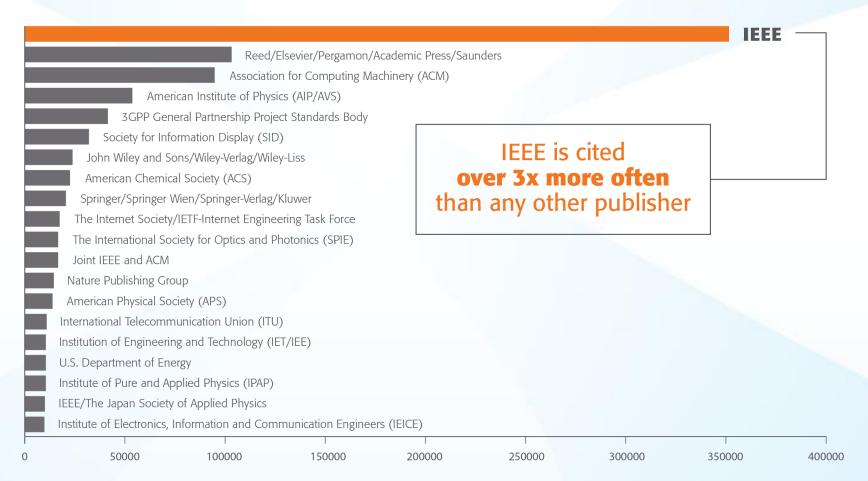
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Source: 1790 Analytics LLC 2015



IEEE Leads US Patent Citations

Top 20 Publishers Referenced Most Frequently by Top 40 Patenting Organizations

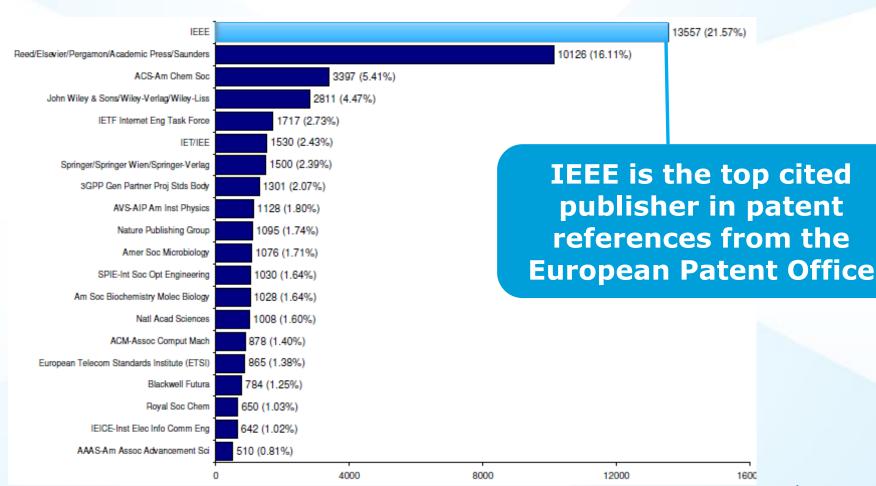


Source: 1790 Analytics LLC 2015. Based on number of references to papers/standards/conferences from 1997-2014



IEEE Leads European Patent Citations

Top 20 Publishers Referenced Most Frequently by Top 25 Patenting Organizations





Source: 1790 Analytics LLC 2012, , Science References from 1997-2011

Technology areas where patents cite IEEE most

Battery

Computer hardware

Computer software

Information storage

Measuring, testing, and control

Medical devices

Nuclear and X-ray

Optics

Power systems

Robotics

Semiconductors

Smart Grid

Solar/Photovoltaic

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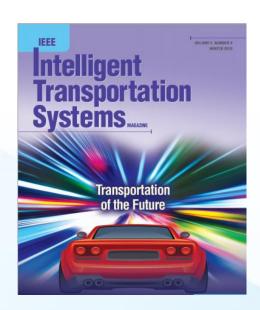
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New IEEE Journals Planned for 2017

In 2017, IEEE will introduce six new journals that will be available for subscription:

- IEEE Communications Standards Magazine
- IEEE Journal of Electromagnetics, RF and Microwaves in Medicine and Biology
- IEEE Transactions on Emerging Topics in Computational Intelligence
- IEEE Transactions on Green Communications and Networking
- IEEE Transactions on Radiation and Plasma Medical Sciences
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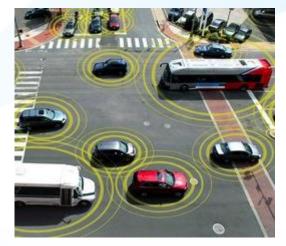




New IEEE Journals Coming in 2016

In 2016, IEEE will introduce four new journals that will be available for subscription:

- IEEE Transactions on **Intelligent Vehicles**
- IEEE Journal on Multiscale and Multiphysics Computational Techniques
- IEEE Robotics and Automation Letters
- IEEE Transactions on Sustainable Computing





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New IEEE Journals from 2015

- IEEE Trans. on Big Data
- IEEE Trans. on **Transportation Electrification**
- IEEE Trans. on Cognitive Communications and Networking
- IEEE Trans. on Computational Imaging
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A sampling of some of the new conferences added in 2015

- **Big Data Software Engineering** (BIGDSE), 2015 IEEE/ACM 1st International Workshop on
- Computational Electromagnetics (ICCEM), 2015 IEEE International Conference on
- DC Microgrids (ICDCM), 2015 IEEE First International Conference on
- Electromagnetic Compatibility and Signal Integrity, 2015 IEEE Symposium on
- Identity, Security and Behavior Analysis (ISBA), 2015 IEEE International Conference on
- Industrial Engineering and Operations Management (IEOM), 2015 International Conference on
- Microwaves for Intelligent Mobility (ICMIM), 2015 IEEE MTT-S International Conference on

- Multimedia Big Data (BigMM), 2015 IEEE International Conference on
- Networking Systems and Security (NSysS), 2015 International Conference on
- Sampling Theory and Applications (SampTA), 2015 International Conference on
- Signal Processing, Informatics, Communication and Energy Systems (SPICES), 2015 IEEE International Conference on
- Smart Cities Conference (ISC2), 2015 IEEE First International



Examples of New IEEE Conferences in 2014



- Internet of Things (WF-IoT), 2014 IEEE World Forum on
- Humanitarian Technology Conference, (IHTC), 2014 IEEE Canada International
- Aerospace Electronics and Remote Sensing Technology (ICARES), 2014 IEEE International Conference on
- Antenna Measurements & Applications (CAMA), 2014 IEEE Conference on
- Consumer Electronics, Taiwan (ICCE-TW), 2014 IEEE International Conference on
- **Energy Conversion** (CENCON), 2014 IEEE Conference on
- Ethics in Science, Technology and Engineering, 2014 IEEE International Symposium on

- Transportation Electrification Asia-Pacific (ITEC Asia-Pacific), 2014 IEEE Conference and Expo
- **Intelligent Energy** and Power Systems (IEPS), 2014 IEEE International Conference on
- Quantum Optics Workshop (QOW), 2014
- Sensor Systems for a Changing Ocean (SSCO), 2014 IEEE
- Wireless and Mobile, 2014 IEEE Asia Pacific Conference on
- Industrial Engineering and Information Technology (IEIT), 2014 International Conference on
- Guidance, Navigation and Control Conference (CGNCC), 2014 IEEE Chinese



Popular IEEE Standards

IEEE 802 Series—IEEE Standard for Ethernet

IEEE 3000 Standards Collection™—Formerly the IEEE Color Books®, this collection will reorganize the 13 Color Books into approximately 70 "dot" standards covering specific technical topics on all facets of industrial and commercial power systems.

IEEE 81-2012™—IEEE Guide for Measuring Earth Resistivity, Ground Impedance, and Earth Surface Potentials of a Grounding System

2012 National Electrical Safety Code® (NESC®)—Sets the ground rules for practical safeguarding of persons during the installation, operation, or maintenance of electric supply and communications lines and associated equipment.

IEEE 43™—IEEE Recommended Practice for Testing Insulation Resistance of Electric Machinery

IEEE 80™—IEEE Guide for Safety in AC Substation Grounding

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 - Original research results presented
 - Clear conclusions are made and supported by the data
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 - Can present preliminary results or highlight recent work
 - Gain informal feedback to use in your research
- Conference articles are typically shorter than journal articles, with less detail and fewer references



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IEEE journal or IEEE conference?

IEEE Journals



 IEEE journals are cited 3 times more often in patent applications than other leading publisher's journals



A high percentage of articles submitted to any professional publication are rejected

IEEE Conferences

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 proceedings are recognized
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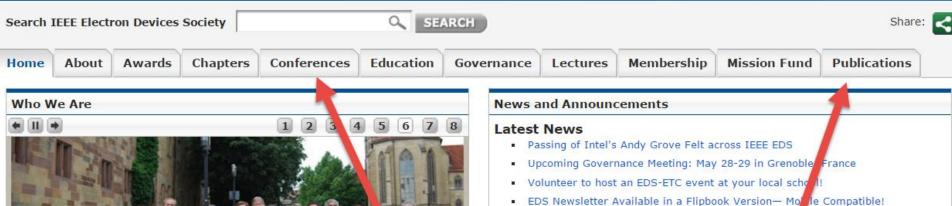
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- 2016 IEEE Global Humanitarian Technology Conference Apr 18th
- 2016 IEEE Compound Semiconductor IC Symp Apr 22nd
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- 2016 IEEE International Integrated Reliability Workshop Jul 11th



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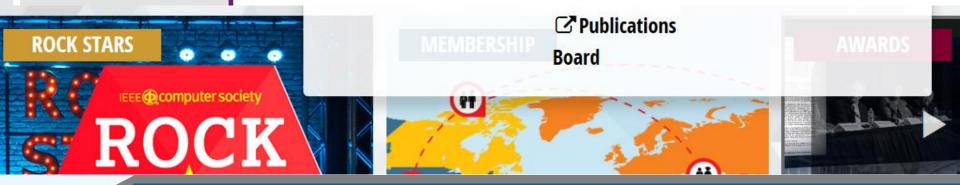
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- Submit to a Magazine
- Submit to a Conference Proceedings
- IEEE Computer Society Style Guide
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- Logo Guidelines
- Submit a Book Proposal (IEEE site)



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- Innovative phased array antennas based on non-regular lattices and overlapped subarrays [call for papers]
- Special Issue on Manipulation, Manufacturing and Measurement on the Nanoscale









Aims & Scope

The theory, design and application of Control Systems. It shall encompass components, and the integration of these components, as are necessary for the construction of such systems. The word 'systems' as used herein shall be interpreted to include physical, biological, organizational and other entities and combinations thereof, which can be represented through a mathematical symbolism. The Field of Interest: shall include scientific, technical, industrial or other activities that contribute to this field, or utilize the techniques or products of this field, subject, as the art develops, to additions, subtractions, or other modifications directed or approved by the IEEE Technical Activities Board.

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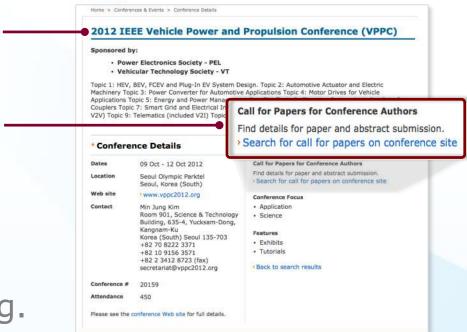


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Notification of acceptance date: 11 Feb 2018

Conference Name ▲ ▼	Conference Date ▲ ▼	Location A 🔻		
2019 IEEE Symposium on Security and Privacy (SP) Full Paper Submission deadline: 16 Nov 2018 Final submission deadline: 31 Mar 2019 Notification of acceptance date: 10 Feb 2019	19 May - 23 May 2019	Hyatt Regency San Francisco 5 Embarcadero Center San Francisco, CA, USA		
2018 IEEE Frontiers in Education Conference (FIE) Abstract submission deadline: 05 Feb 2018 Full Paper Submission deadline: 23 Apr 2018 Final submission deadline: 09 Jul 2018 Notification of acceptance date: 21 May 2018	03 Oct - 06 Oct 2018	TBD TBD San Jose, CA, USA		
2018 IEEE World Congress on Computational Intelligence (WCCI) Full Paper Submission deadline: 01 Feb 2018 Final submission deadline: 01 May 2018 Notification of acceptance date: 01 Apr 2018	08 Jul - 13 Jul 2018	Windsor Barra Convention Centre Rua Martinho de Mesquita Barra da Tijuca Rio de Janeiro, Brazil		
2018 IEEE International Symposium on Information Theory (ISIT) Abstract submission deadline: 07 Jan 2018 Full Paper Submission deadline: 07 Jan 2018 Final submission deadline: 22 Apr 2018 Notification of acceptance date: 01 Apr 2018	17 Jun - 22 Jun 2018	Vail Cascade 1300 Westhaven Drive Vail, CO, USA		
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IEEE

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Structure



Paper Structure

Elements of a manuscript

Title

Abstract

Keywords

Introduction

Methodology

Results/Discussions/Findings

Conclusion

References





Paper Structure Title

An effective title should...

- •Answer the reader's question: "Is this article relevant to me?"
- •Grab the reader's attention
- •Describe the content of a paper using the fewest possible words
 - Is crisp, concise
 - Uses keywords
 - Avoids jargon





Paper Structure

Good vs. Bad Title

A Human Expert-based Approach to Electrical Peak Demand Management

VS

A better approach of managing environmental and energy sustainability via a study of different methods of electric load forecasting



Paper Structure

Good vs. Better Title

An Investigation into the Effects of Residential Air-Conditioning Maintenance in Reducing the Demand for Electrical Energy

VS

"Role of Air-Conditioning Maintenance on Electric Power Demand"



Paper Structure Abstract

Why you did A "stand alone" condensed version of the article No more than 250 words; What you did written in the past tense Uses keywords How the results and index terms were useful, important & move the field forward Why they're useful & important & move the field forward



Abstract:

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The abstract must be a **concise yet comprehensive reflection of what is in your article**. In particular, the abstract must be as follows.

- 1) Self-contained, without abbreviations, footnotes, or references; it should be a **microcosm of the full article**
- 2) Between **150-250 words**. Be sure that you adhere to these limits; otherwise, you will need to edit your abstract accordingly.
- 3) Written as **one paragraph**, and should **not contain** displayed **mathematical equations or tabular material**.
- 4) Should include **three or four different keywords or phrases**, as this will help readers to find it. It is important to avoid over-repetition of such phrases as this can result in a page being rejected by search engines.
- 5) Ensure that your abstract **reads well and is grammatically correct**.



Paper Structure

Good vs. Bad Abstract

The objective of this paper was to propose a human expert-based approach to electrical peak demand management. The proposed approach helped to allocate demand curtailments (MW) among distribution substations (DS) or feeders in an electric utility service area based on requirements of the central load dispatch center. Demand curtailment allocation was quantified taking into account demand response (DR) potential and load curtailment priority of each DS, which can be determined using DS loading level, capacity of each DS, customer types (residential/commercial) and load categories (deployable, interruptible or critical). Analytic Hierarchy Process (AHP) was used to model a complex decision-making process according to both expert inputs and objective parameters. Simulation case studies were conducted to demonstrate how the proposed approach can be implemented to perform DR using real-world data from an electric utility. Simulation results demonstrated that the proposed approach is capable of achieving realistic demand curtailment allocations among different DSs to meet the peak load reduction requirements at the utility level.

Vs

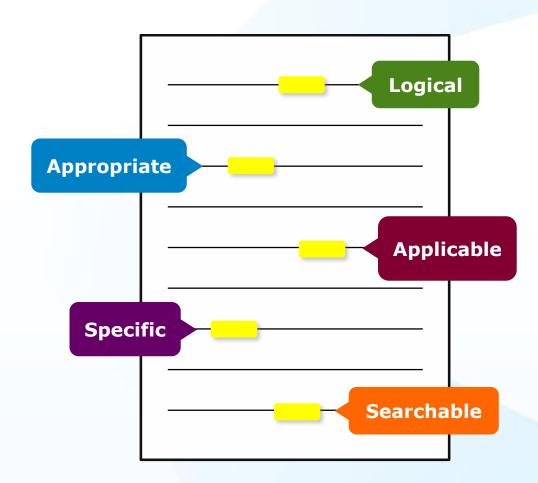
This paper presents and assesses a framework for an engineering capstone design program. We explain how student preparation, project selection, and instructor mentorship are the three key elements that must be addressed before the capstone experience is ready for the students. Next, we describe a way to administer and execute the capstone design experience including design workshops and lead engineers. We describe the importance in assessing the capstone design experience and report recent assessment results of our framework. We comment specifically on what students thought were the most important aspects of their experience in engineering capstone design and provide quantitative insight into what parts of the framework are most important.

First person, present tense
No actual results, only describes the organization of the paper



Paper Structure Keywords

Use in the Title and Abstract for enhanced Search Engine Optimization





IEEE Keywords

Bit rate, Decoding, Encoding, Parallel processing, Video coding

Authors Keywords

High Efficiency Video Coding (HEVC), parallel programming, video coding

INSPEC: Controlled Indexing

parallel processing, video coding

INSPEC: Non-Controlled Indexing

12-core system, H.264-advanced video coding, HEVC parallelization approaches, OWF, WPP, frequency 3.33 GHz, high efficiency video coding, overlapped wavefront, parallel efficiency, parallel friendliness, parallel scalability, parallelization proposals, tiles, wavefront parallel processing



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Keywords should be taken from the taxonomy provided in ScholarOne Manuscripts. Using the keywords from the keyword list is essential to the review process because ScholarOne Manuscripts links them to names of potential reviewers who are associated with that area of expertise, thereby expediting the review process. We encourage all users to include keywords as part of their account information. If you currently do not have keywords included as part of your account information, you may add them by clicking the "edit your information" button on the main menu. Scroll down the page until you reach the "keywords" box. You may then select the keywords that apply to you from the list provided.

https://www.computer.org/web/peer-review/journals#Length of Review Process



Paper Structure Introduction

- A description of the problem you researched
- It should move step by step through, should be written in present tense:

Generally known information about the topic

Prior studies'
historical
context to your
research

Your hypothesis and an overview of the results

How the article is organized

- The introduction should <u>not be</u>
 - Too broad or vague
 - More then 2 pages



Paper Structure Methodology

- Problem formulation and the processes used to solve the problem, prove or disprove the hypothesis
- Use illustrations to clarify ideas, support conclusions:

Tables

Present representative data or when exact values are important to show



Figures

Quickly show ideas/conclusions that would require detailed explanations



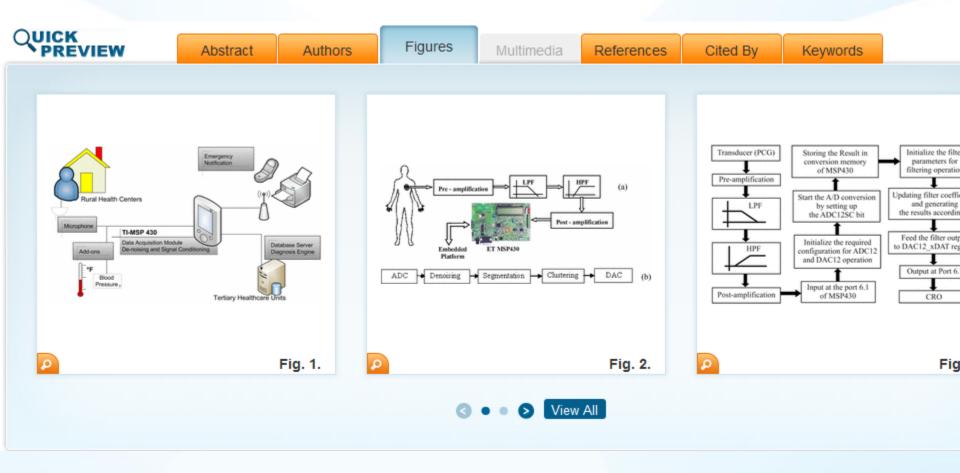
Graphs

Show relationships between data points or trends in data



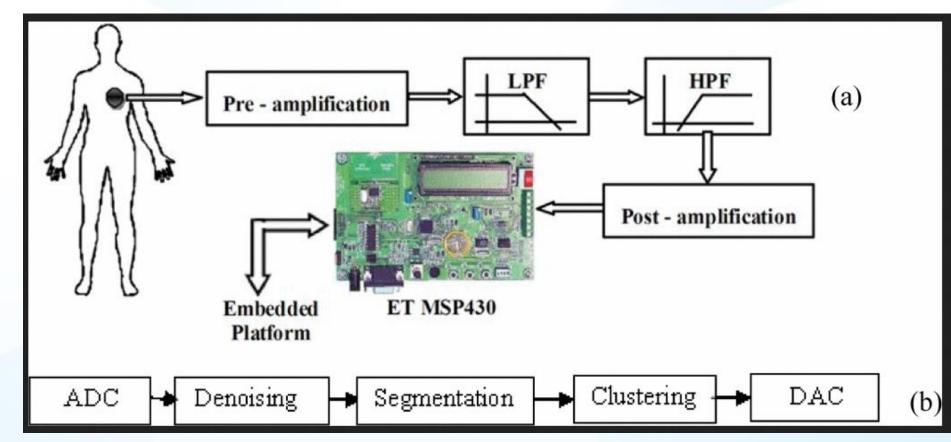


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Equations in TeX Source in HTML version

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```
 $\eqalignno{\{\rm\ HS\}_{\{\rm\ recover\}} \& \|=\| \left(1 - \{E\eft\{x_{\{\rm\ HS\}}^2 \setminus \{rm\ reduct)\} \right} - E\eft\{\{y^2 \setminus \{rn\ right\}\} \right} \right) }
```

and NOISE reduction are computed in terms of percentages (see Table 1)

$$\text{HS}_{\text{recover}} = \left(\frac{1 - E\{x_{\text{HS}}^{2}(n)\} - E\{y^{2}(n)\}}{E\{x_{\text{HS}}^{2}(n)\}}\right) \times 100\%$$

$$\text{NOISE}_{\text{reduction}} = \left(\frac{E\{x_{\text{hs_noi}}^{2}(n)\} - E\{y^{2}(n)\}}{E\{x_{\text{hs_noi}}^{2}(n)\}}\right) \times 100\%$$

$$E\{x_{\text{hs_noi}}^{2}(n)\}$$



Paper Structure Results/discussion

Demonstrate that you solved the problem or made significant advances

Results: Summarized Data

- Should be clear and concise
- Use figures or tables with narrative to illustrate findings

Discussion: Interprets the Results

- Why your research offers a new solution
- Acknowledge any limitations

the SC algorithm over the whole range of w values increase to 3-4 K, except for the TIGR: to database, with an RMSE of 2 K. This last result is explained by the w distribution, which is biased toward low values of w in this database. When only atmospheric profiles with to values lower than S g - cm - 2 are selected, the SC algorithm provides RMS around 1.5 K, with almost equal values of bias and standard deviation, around 1 K in both cases (with a negative bias, thus the SC underestimates the LST). In contrast, when only we values higher than 3 g - cm⁻² are considered, the SC algorithm. provides RMSEs higher than 5 K. In these cases, it is preferable to calculate the atmospheric functions of the SC algorithm directly from (3) rather than approximating them by a polynomial fit approach as given by (4).

V. DISCUSSION AND CONCLUSION The two Landsat-S TIR bands allow the intercomparison

of two LST retrieval methods based on different physical such as the SC (only one TIR band required) fams (two TIR bands required). Direct inversion e transfer equation, which can be considered orithm, is assumed to be a "ground-truth" **Discussion** and L_d) is accurate enough. The SC algoin this letter is a continuation of the previous SC veloped for Landsat-4 and Landsat-5 TM sensors, ne ETM+ sensor on board the Landsat-7 platform [9], and it could be used to generate consistent LST products from the historical Landsat data using a single algorithm. An advantage of the SC algorithm is that, apart from surface emissivity, only water vapor content is required as input. However, it is expected that errors on LST become unacceptable for high water upper contents (e.g., > 3 g \cdot cm⁻²). This problem can be purify solved by computing the atmospheric functions directly from τ , L_{∞} , and $L_{\mathcal{L}}$ values [see (5)], or also by including air temperature as input [15]. A main advantage of the SW algorithm is that it performs well over global conditions and, thus, a wide range of water vapor values; and that it only requires water vapor as input (apart from surface emissivity at the two TIR bands). However, the SW algorithm can be only applied to the new Landant-S TIRS data, since previous TM/ETM sensors only had one TIR band.

The LST algorithms presented in this letter were tested with simulated data sets obtained for a variety of global atmospheric conditions and surface emissivities. The results showed RMSE values of typically less than 1.5 K, although for the SC algorithm, this accuracy is only achieved for w values below 3 g - cm⁻². Algorithm testing also showed that the SW errors are lower than the SC errors for increasing water vapor, and vice versa, as demonstrated in the simulation study presented in Sobrino and Jiménez-Muñoz [18]. Although an extensive validation exercise from in sits measurements is required to assess the performance of the two LST algorithms, the results obtained for the simulated data, the sensitivity analysis, as well as the previous findings for algorithms with the same mothemotical structure give confidence in the algorithm accuracies

Results

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We then have

$$(P_t^{a,+} + P_t^{a,-})^2 - (P_t^{a,+} - P_t^{a,-})^2 + 4P_t^{a,+}P_t^{a,-}$$

 $< (\hat{P}_t^{a,+} - \hat{P}_t^{a,-})^2 + 4\hat{P}_t^{a,+}\hat{P}_t^{a,-}$
 $- (\hat{P}_t^{a,+} + \hat{P}_t^{a,-})^2.$ (32)

Since $P_i^{h,+} - P_i^{h,-} = P_i^{h,+} - P_i^{h,-}$, we then have $P_i^{h,+} < P_i^{h,+}$, and $P_i^{h,-} < P_i^{h,-}$. Because the operational cost is an increasing function of $\{P_i^{h,+}, P_i^{h,-}\}$, we obtain that

$$c_{n/m}(P_t^{s,+}, P_t^{s,-}) < c_{n/m}(\hat{P}_t^{s,+}, \hat{P}_t^{s,-}).$$
 (33)

Therefore the optimal pair $\{P_i^{h,+},P_i^{h,-}\}$ must satisfy that $P_i^{h,+}P_i^{h,-}=0$, i.e., only one of $P_i^{h,+},P_i^{h,-}$ can be non-zero.

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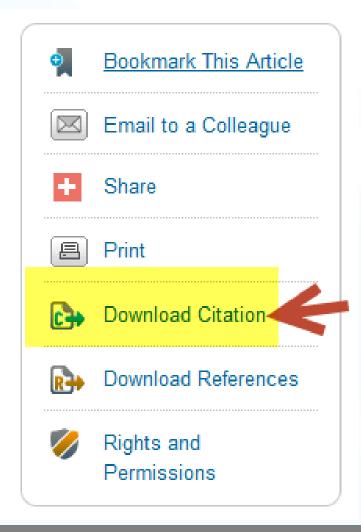
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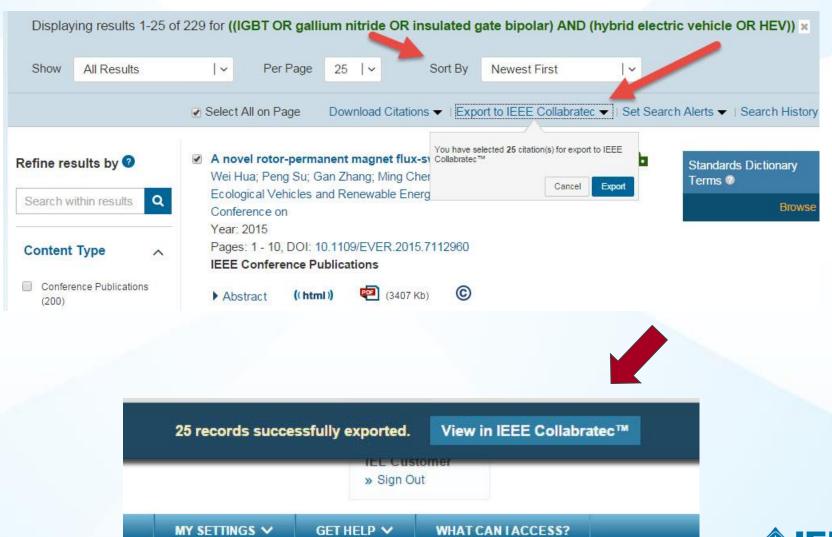
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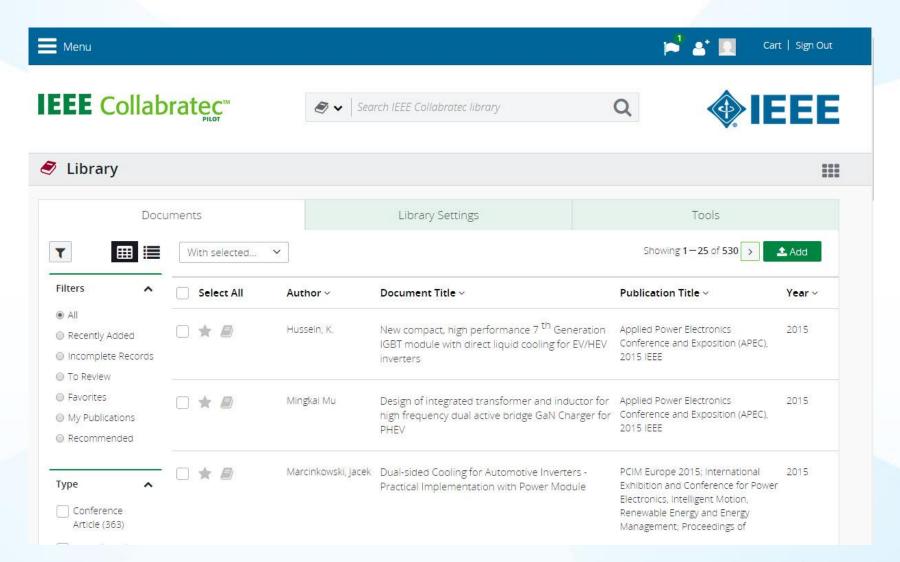


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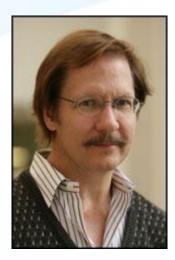
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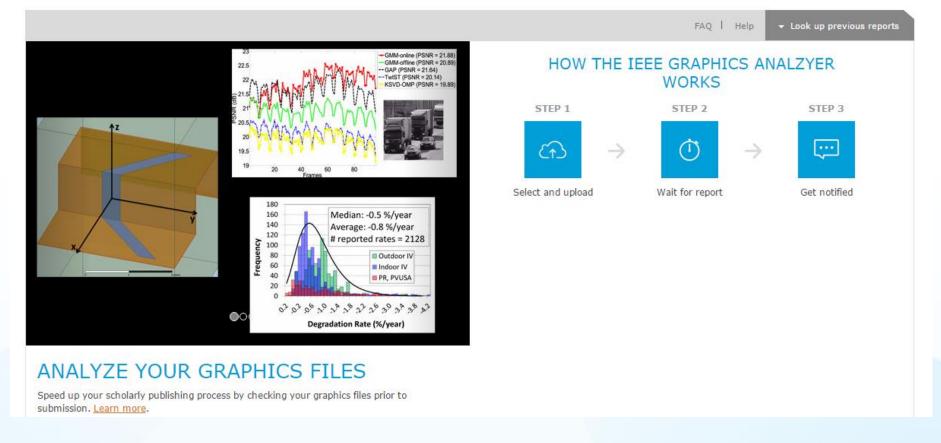
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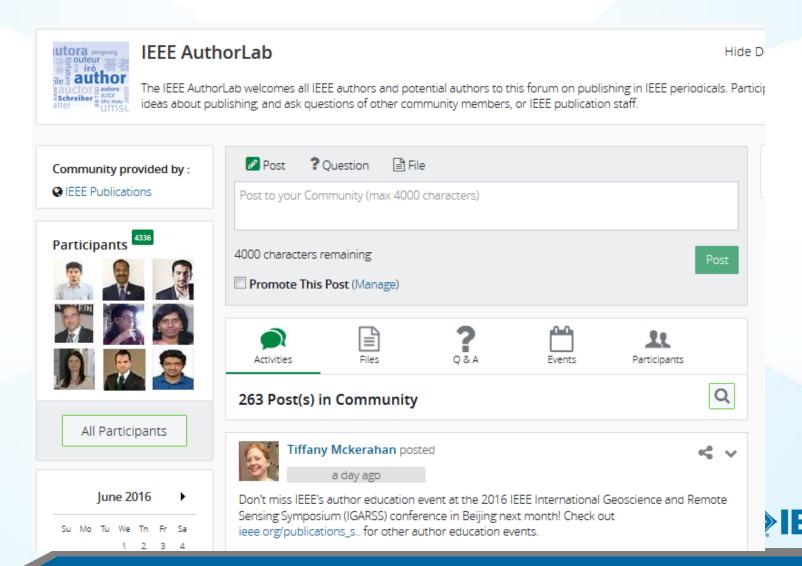
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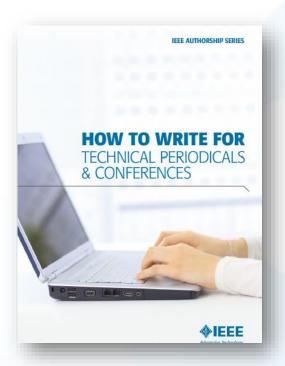
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